

ABSTRACT

A system and method for reducing an apparent height of a board system are provided.

The board system may include, for example, a carrier, a component, a printed circuit board and/or a solder material. The component is mounted on a first side of the carrier. The

5 printed circuit board has a hole that is structured to accommodate the component. The solder material solders the carrier to the printed circuit board and provides a structural bond

between the carrier and the printed circuit board. At least one portion of the solder material provides an electrical coupling between the carrier and the printed circuit board and at least

one portion of the component is maintained in the hole after the carrier is soldered to the

10 printed circuit board.